



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

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Examiner: Phat X. CAO

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Application No.: 10/632,549

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Group Art Unit: 2814

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Filed: August 2, 2003

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Date: April 12, 2005

Title: Semiconductor multi-package module
having wire bond interconnect between
stacked packages

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on April 12, 2005.

Signed

Bill Kennedy

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

Applicant responds as follows to the Office action mailed October 12, 2004.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the **Listing of Claims** which begins on page 3 of this paper.

Remarks begin on page 5 of this paper.